

Fuseholder Open Design, 5 x 20 / 6.3 x 32 mm, SMD, IEC: 500 VAC, UL/CSA: 600 VAC/DC, Cover, IEC 60355-1



500 VAC · 4 W/10 A (VDE) · 600 VAC/DC · 16 A (UL/CSA)



Description

- Fuseholder for 500 VAC applications
- Meets the new requirements of IEC 60335-1 Ed. 4.0 for appliances in unattended use (clause 30.2.3). This includes the enhanced requirements of glow wire tests acc. to IEC 60695-2-11 to -13. Order number: 0031.8242 / 0031.8242.F1
- Fuse block accepts 5x20 or 6.3x32 fuse-links

Standards

- IEC 60127-6
- UL 4248-1 / UL 512
- CSA C22.2 no. 39

Approvals

- VDE License Number: 40008993 (250V) + 40018378 (500V)
- UL File Number: E39328

Applications

- Equipment with three-phase supply (400 VAC)
- Industrial electronic


References

[General Product Information](#)
[Packaging Details](#)

Weblinks

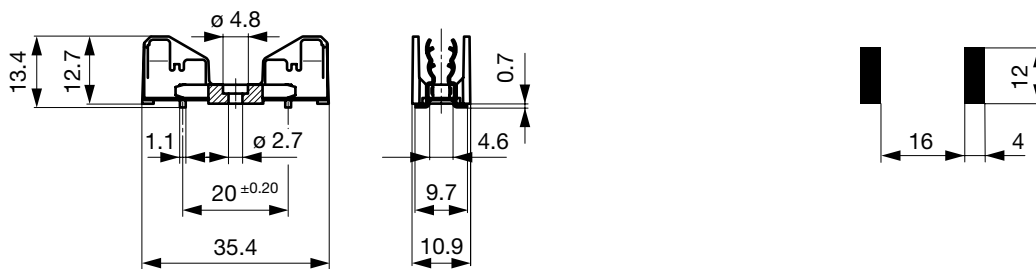
[Approvals, RoHS, CHINA-RoHS, e-Store, Distributor-Stock-Check, Accessories, Product Change Notification \(PCN\)](#)

Technical Data

Fuse-Link	5 x 20 or 6.3 x 32 mm
Mounting	PCB
Mounting	Screw or Rivet
Terminal	Solder SMT
Rated Voltage	500 VAC (VDE), 600 VAC/DC (UL/CSA)
Rated Current	10 A (VDE), 16 A (UL/CSA)
Rated Power Acceptance IEC	4 W / 10 A @ Ta 23 °C Admissible power acceptance at higher ambient temperature see derating curves
Degree of Protection	IP 00 / IP 20
Protection Class	Suitable for appliances with protection class 1 or 2 acc. to IEC 61140
Admissible Ambient Air Temp.	-40 °C to 85 °C
Climatic Category	40/085/21 acc. to IEC 60068-1
Material: Socket	Thermoplastic, black, UL 94V-0
Material: Terminals	Tin-Plated Copper Alloy
Unit Weight (Socket/Cap)	3.7 g
Storage Conditions	0 °C to 60 °C, max. 70% r.h.
Product Marking	 Type, Voltage, Power Acc./Current Rating, Approvals

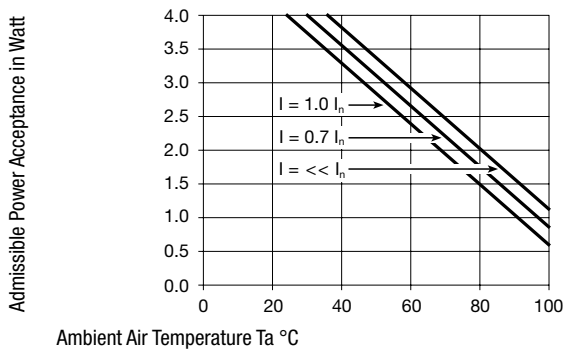
Soldering Methods	Reflow (see variants)
Solderability	245 °C / 3 sec acc. to IEC 60068-2-58, Test Td
Resistance to Soldering Heat	240 - 260 °C / 20 - 40 sec acc. to IPC/JEDEC J-STD-020D
Contact Resistance	< 5 mΩ at 20 mV
Dielectric Strength	> 3 kV between L-N (50 Hz; 1 min)
Impulse Withstand Voltage	> 4 kV between L-N
Insulation Resistance	> 10 MΩ between L-N (500 VDC; 1 min)
Overvoltage Category	I - III acc. to IEC 60664-1
Pollution Degree	2 acc. to IEC 60664-1
Resistance to Vibration	acc. to IEC 60068-2-6, test Fc

Abmessungen



Solder pads

Derating Curves for Fuseholders



Variants

Holder	Material	Reflow Condition	Remark	Order Number
●	Thermoplastic	(acc. to JEDEC J-STD-020C), T _p =240 +0/-5 °C, t _p = 20-40 s	-	0031.8241
●	Spec. Thermoplastic 2	acc. to JEDEC J-STD-020C, T _p =260 +0/-5 °C, t _p = 20-40 s	Approvals pending	0031.8242

Spec. thermoplastic meet the new requirements of IEC 60335-1 Ed. 4.0 for appliances in unattended use (clause 30.2.3). This includes the enhanced requirements of glow wire tests acc. to IEC 60695-2-11 to -13.

Packaging Unit xxxx.xxxx.F1 Bar Packaging (20x50 pcs.)

Accessories

Description



Cover OGD, OGD-SMD
Cover for Holder OGD, OGD-SMD

Reflow-Cover

0853.0917